

# Electronic Design and Solution Fair 2007

with FPGA/PLD Design Conference



07

World-Leading Technologies – Yours to Discover

## Exhibition Outline

Period : Thursday - Friday, January 25 - 26, 2007

Place : Pacifico Yokohama, Kanagawa, Japan

Japan Electronics and Information Technology Industries Association JEITA

[www.edsfair.com](http://www.edsfair.com)

# Trade Show & Conference Spotlight Key Design Solution Technologies

## On the Announcement of the Electronic Design and Solution Fair 2007



### Naoyuki Akikusa

Chairman,  
Japan Electronic and  
Information Technology  
Industries Association (JEITA)

(also Chairman and  
Representative Director,  
Fujitsu Limited)

The Japan Electronics and Information Technology Industries Association (JEITA) will be hosting the Electronic Design and Solution Fair 2007 at the Pacifico Yokohama on January 25 & 26, 2007. This will be the 14th time that this event has been held, including EDSFair's predecessor, the EDA TechnoFair.

The goal of EDSFair is to introduce and disseminate information about the latest design solutions, design technologies, and EDA technologies required to produce the semiconductors and electronic systems for the IT applications that will form the foundation of the future information society, whose citizens will enjoy a ubiquitous computing environment. The fair thus contributes to the development of electronics and other IT-related industries.

From the second half of last year there have been signs of recovery in Japan's electronics industry, with both production and exports on the rise, and this recovery has been gathering momentum this year. This is especially noticeable in the fields of semiconductors and displays, where a growing number of companies are increasing their capital investment.

JEITA forecasts that this year Japan's electronics industry will achieve a 2.3% increase over last year in its domestic production. Depending on business conditions in the second half, it is possible that the final figure may even exceed ¥20 trillion. Furthermore, this upturn is not limited in scope: everything from components and semiconductors to home IT appliances and mobile phones are expected to benefit from growing demand.

Nevertheless, facing increased competition in the international arena, Japan's industries as a whole need to enhance their competitive power, and this requires innovations on many different levels. It is therefore of critical importance that we foster the industry's human resources – particularly the engineers needed to realize these innovations.

"World-Leading Technologies – Yours to Discover" is the theme of this Electronic Design and Solution Fair 2007. You will find on display world-class, cutting-edge technologies tailored for an age that demands new solutions. There are a variety of seminars and a conference offering a wide range of up-to-date information. There are open sessions catering to young engineers, new zones that bring together both Japanese and foreign venture businesses, as well as initiatives for promoting substantive technical exchanges between industry, academia and government.

It is the fervent desire of all of us in JEITA that EDSFair will contribute to enhancing the design technologies available to Japan's electronic and IT industries, and also that both visitors and exhibitors will be able to make the best use of the opportunities afforded by this event for conducting effective and fruitful exchanges of information, and for generating new business.

We greatly look forward to the participation of many companies and professionals in this upcoming trade show.

## Exhibition Outline



### Objectives:

The age of chips with millions of gates is at hand, and advanced development to upgrade device performance, reduce risks, costs and power consumption, and embed software is proceeding at an unprecedented pace around the world. Reflecting this trend, EDSFair assembles specialized information on advanced device technologies, such as EDA, ASICs (Application Specific Integrated Circuits), FPGA/PLDs (Field Programmable Gate Array/Programmable Logic Devices), IP re-usage, embedded software and design services. Also featured are the latest trends and targets for further development of electronics technologies.

- Name: **Electronic Design and Solution Fair 2007 (EDSFair 2007)**
- Schedule: Thursday, January 25 & Friday, January 26, 2007  
10:00 a.m. to 6:00 p.m.
- Location: Pacifico Yokohama (Exhibition Hall, Annex Hall)  
1-1-1, Minato Mirai, Nishi-ku, Yokohama 220-0012
- Admission: Exhibition: Free (registration required at show entrance)  
Conferences: Fees will be charged for some conferences
- Sponsor: Japan Electronics and Information Technology Industries Association **JEITA**
- Cooperation: Electronic Design Automation Consortium 
- Support: (expected) Ministry of the Economy, Trade and Industry, Japan (METI)  
Embassy of the United States of America in Japan  
Distributors Association of Foreign Semiconductors (DAFS)  
City of Yokohama
- Assistance: (expected) Institute of Electronics, Information and Communication Engineers (IEICE)  
Information Processing Society of Japan (IPSJ)  
Japan Electronics Packaging and Circuits Association (JPCA)
- Jointly held event: The 14th FPGA/PLD Design Conference
- Concurrently held events: System Design Forum 2007  
ASP-DAC 2007 (Asia and South Pacific Design Automation Conference 2007)
- Management: Japan Electronics Show Association (JESA)

## One of the Three Largest Trade Shows in the World

EDSFair is one of the three largest trade shows in the world in the field of semiconductor and electronic system design, along with the US Design Automation Conference (DAC) and Design, Automation Test in Europe (DATE). Here all the latest technologies from around the world can be found at one venue.



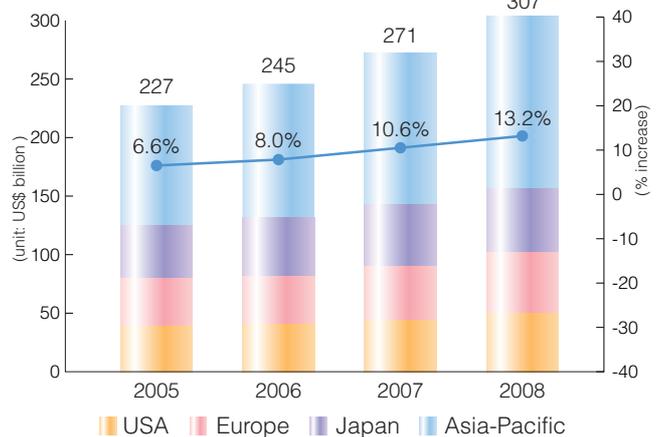
**DATE**      **EDSFair**      **DAC**



## Continuously Growing Semiconductor Market

Japan's semiconductor market is expected to average 4% growth annually thanks to robust demand for consumer digital equipment such as flat panel display TVs and the widespread adoption of 3G mobile phones. Further growth is expected as the global market as a whole adopts the latest technologies that enable ubiquitous computing.

Year-on-year increases to 2008



Source: WSTS

## For the Next Generation

At the EDSFair discover a world of innovative new technologies rarely seen in day-to-day business. Actively promoting human resource training, this event provides young engineers with opportunities to gather the latest information. EDSFair is a business trade show engineered specifically to foster development of the industry.

### Emerging Company Area

This is a new area designed especially for domestic and overseas emerging companies that offer industry solutions. So as to provide the latest information to design engineers, this area has a presentation stage as well as booth areas set aside for business discussions.

### Special Presentation Stage

The Special Presentation Stage is mainly used for talks aimed at young engineers who are actively involved in ongoing projects. New vendors will be introduced, as will new discoveries.

### University Plaza

In order to promote increased collaboration between the business and academic worlds, as well as to foster new developments in Japan's design technologies, EDSFair offers an opportunity for Japanese and foreign universities to present the results of their research projects.



## Enhancing Customer Satisfaction

A number of seminars and mini-events are planned to meet the needs of design engineers. This will make the EDSFair the ideal venue for better understanding customer requirements and thus increasing business opportunities.

### Product demonstrations in booths and suites

By making use of the synergies generated by presentations at open booths and more personalized suite-based demonstrations for select groups, exhibitors will be able to gather information on potential customer needs from different perspectives.

### Exhibitor Seminars

Exhibitors can effectively demonstrate their technologies and products free of charge at seminars. Each year, over 3,000 visitors attend more than 100 of these seminars, making this a very popular part of the trade fair offering something for all participants.



### FPGA/PLD Design Conference

This is the only conference in Japan that specializes in FPGA/PLD and it is an invaluable opportunity to obtain the latest information on FPGA/PLD – design methods, business activities and trends.

### Concurrently held events

- System Design Forum  
Talks on SystemC and SystemVerilog organized by the JEITA EDA Technical Committee
- ASP-DAC (Asia and South Pacific Design Automation Conference)  
International conference for design and EDA technologies. The forum for Japanese design engineers is also popular.

# How to Maximize the Potential of Your Business at the EDSFair

## EDSFair is an Important Centerpiece of Businesses in Japan.

EDSFair is a large-scale tradeshow sponsored by JEITA that showcases the latest IC design tools, methodologies, manufacturing solutions, design services, and many other technologies that affect today's electronic circuits and systems. Participating vendors will exhibit products offering innovative technologies that are designed to meet customer requirements.

EDSFair offers you a great chance to acquire new sales opportunities and is an ideal venue to promote one's products.



### EDSFair is:

- Scheduled to be held at the same time as when domestic semiconductor and equipment manufacturers are allocating their budgets so it is perfectly timed for your sales activities.
- A great opportunity to enhance the brand image of exhibitors.
- An ideal venue for identifying customer needs that are difficult to obtain normally in business operations. And this feedback can be used as marketing data to enhance sales opportunities.

The EDSFair represents a tremendous opportunity to boost the potential of your business.

## Keys to Exhibition Success

### Extensive

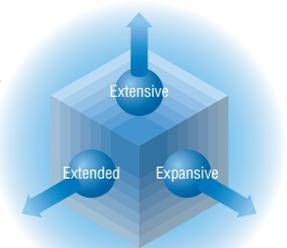
Use the power of information gained at EDSFair as the mainstay of your public relations activities.

### Extended

Continually use the power of information gained at EDSFair to support your sales activities before, during and after the event.

### Expansive

Maximize exhibition effectiveness by making participation at the EDSFair a company-wide affair.



Keys to Exhibition Success

### Coordinate Your Schedule with the EDSFair:

Increase exhibition effectiveness by timing the release of information on new products and technologies with the fair timetable.

- Set product introduction schedules to match the start of the EDSFair.
- Conduct press releases of new products and technologies prior to the fair.
- Take advantage of the popular EDSFair official Web site.
- Take advantage of PR opportunities offered by EDSFair.
- Link overseas PR activities with the EDSFair.



### Match Booth Design with the EDSFair:

Ensure that the booth design facilitates communications with customers.

- Ensure that the booth is designed for easy entry.
- Allocate wide spaces within the booth.
- Presentations should be held within the booth to entice visitors to enter.
- Positioning the meeting table close to the demonstration area is an effective setup.
- Use of suite-room type booths is most effective for communicating with special customers.



### Match PR Activities with the EDSFair:

Get all employees including the top management to conduct promotional activities together with the timetable of the EDSFair.

- Enhance your company's presence by having the top management announce new products and corporate strategies.
- Use the EDSFair as a venue to announce important alliances or partnerships.
- Enhance corporate motivation by maximizing the most important characteristic of exhibitions: creating a sense of unity via effective events.
- Ensure that the top management spends some time in the booth to support sales activities.



### Match Promotional Activities with the EDSFair:

Conduct effective presentations with information not available in the booth.

- Carefully review promotional tools, such as product catalogs and leaflets.
- Purposely release in-depth information by hosting seminars and tutorials; design seminar programs for use in marketing activities after the exhibition.
- Take advantage of commemorative novelty goods offered at the exhibition site.
- Create effective visitor questionnaires to collect valuable customer data.



### Match Sales Activities with the EDSFair:

Strengthen sales planning with the EDSFair and carry out continuous sales activities before, during and after the fair.

- Prior to the fair, assign customer lists into categories such as VIP, important customers or potential customers.
- Prior to the fair, develop sales strategies and planning for each category.
- Prior to and during the fair, send direct mail and make appointments with important customers for the exhibition period.
- During the fair, contact customers who did not visit your booth on the initial day of the fair.
- After the fair, develop continuing sales strategies and maximize information gathering.

### Match Advertising with the EDSFair:

Integrate important promotional activities with various advertising media with the timetable of the EDSFair.

- Take advantage of the EDSFair ads planned for insertion in specialized magazines.
- Include your EDSFair booth number in ads prior to the exhibition.
- Ensure maximum customer pre-notification by using the EDSFair advertising media.



# Supplementary Support Services Offered Only for EDSFair Exhibitors

## Use of Seminar Rooms (charged service)

Exhibitors can use seminar rooms available in 3 sizes (type A, B or C) to conduct effective presentations of technology and product seminars. Seminar information will be released in the official Web site and information leaflets prior to the fair.



## Use of Suites (charged service)

Suites that serve as executive-style meeting rooms allow exhibitors to communicate with small groups or special customers in a relaxed atmosphere. Make good use of suites to introduce strategic or yet-to-be announced products to a specific audience.



## Information Leaflets (in Japanese) and Free Envelopes

200 sets of direct mail for visitors will be distributed free of charge for each booth. The number of sets available may vary depending on the number of booths. Each set will include an information leaflet with envelope, which can be used to invite important customers to your booth and the fair.



## Placement in the Guidebook (free)

A guidebook will be distributed to all visitors free of charge. Visitors can use the guidebook as a reference tool after the fair, making it useful as a long-term promotional material. Charged ad spaces will also be available.



## Web Site Placement (free)

EDSFair 2007 official Web site can be browsed not only by potential visitors but also by those involved in the industry and the press.

Important exhibitor products can be introduced in the site and we will offer links to the Web sites of exhibitors to help promote products and the exhibitor during and after the event. Also, charged banner ads on the Web will also be available before and during the event.



Sample of charged ad space

## Ad Placement on the Fair Map (charged service)

Block ads can be inserted in the map distributed during the fair.



## EDSFair Official e-Mail Service (charged service)

Customized exhibitor information messages can be inserted in the official e-mail address of the EDSFair, which will be sent by the management office to prospective visitors two months prior to the fair. This will be an effective tool to attract more visitors.



## Distribution of Press Releases (free)

Exhibitor press releases will be distributed to the media at the pressroom located at the site to make information on key products and new technologies readily available at the EDSFair.



## On-site Signage Ads (charged service)

Ads can be placed on a wide variety of on-site signboards, serving as powerful tools to attract visitors to your booth.



For further details, please refer to page 7, *Guide to Application of Support Services*.

# Guide to Exhibition Regulations

## 1 Scope of Exhibits

- 1.1. Hardware solutions**  
System LSI, ASIC/ASSP, MPU/MCU/DSP, FPGA/PLD and others
- 1.2. Hardware development (EDA)**
- IC design tools  
System level design (higher than RTL), logic design (RTL to net list), logic verification, analog design/verification, physical implementation, physical verification/analysis, signal integrity analysis, test (DFT/BIST/ATPG/others), DFM (OPC/RET/PSM/LRC/TCAD/others) and others
  - PCB design tools  
Schematic capture, PCB layout, PCB signal integrity, analog design/verification and others
  - System in package (Sip) tools
- 1.3 Software solutions**  
Embedded OS, device drivers, firmware/middleware and others
- 1.4 IC tester/analyzer**  
IC testers, PCB testers, analyzers and others
- 1.5 IP core, macro, cell libraries**
- 1.6 Embedded processor development environments**  
Reconfigurable processors, ICE, debuggers, microcomputer CASE, compilers/cross compilers, simulators, hardware/software co-design environments and others
- 1.7 Design service-related**  
Design houses/design services, design consulting, IP distribution services and others
- 1.8 Design infrastructure (WS/PC, Network)**
- 1.9 Design data management tool**
- 1.10 Mask shop, foundry**
- 1.11 University (R&D), consortium**
- 1.12 PR-related**  
Publications and others

## 2 Eligible Exhibitors

- 2.1 Manufacturers, trading companies, publishing companies and organizations with operations applicable to Section 1 above.**
- 2.2 Applications through representatives such as advertising agencies will not be accepted.**

## 3 Configuration and Number of Booths

Configuration	No. of booths applied for
1 row	1, 2, 3, 4, 5, 6
2 rows	4, 6, 8, 10, 12
3 rows	9, 12, 15, 18
4 rows	16
Blocks	20, 25, 30, 35, 40, 45, 50

## 4 Booth Specifications

- 4.1 Booths in rows**  
Each booth is 2,970 mm (W) x 2,970 mm (D).
- 4.2 Block area**  
The total area of each block area will be calculated by multiplying the unit area of a booth (9m<sup>2</sup>) by the number of booths specified. Booths will then be rearranged in a space with a width-depth ratio of 2:1 to 1:1. This will be indicated in a design drawing at the time of booth lottery.
- 4.3 Booth height**  
Maximum booth height is 2,700 mm. This limit may be exceeded by 300 mm in exceptional cases of installing minimum lighting and/or sound equipment (small-size speakers, etc.), if inevitable for construction reasons.

## 5 Fees

The exhibition fees per booth are as follows:

Exhibitor classification	Apply by Sept. 8, 2006	Apply after Sept. 9, 2006
JESA member	¥262,500 (including tax)	¥273,000 (including tax)
Other	¥294,000 (including tax)	¥304,500 (including tax)

The aforementioned fees include:

- 5.1. Basic panels**  
Exhibitors with in-row booths will receive system panels for the rear of their booths and, if other booths are arranged adjacently, for the side(s). There will be no dividing panels on the aisle sides of booths. Basic panels will not be provided for exhibitors in block areas of 20 booths or more.
- 5.2. Basic power supply line**  
Installation of electric power supply lines for 1kW (max) single-phase 100V or 200V, including one outlet for total switching per booth (Note: Electricity consumption is charged according to the table in section 6.4 below.)
- 5.3. 200 information leaflets (in Japanese) and envelopes per booth**
- 5.4. Exhibitor and contractor badges (10 and 5 per booth)**
- 5.5. Exhibitor introduction space in Guidebook**
- 5.6. Exhibitor introduction space on Fair Web site**

## 6 Additional Costs

Exhibition fees mentioned in section 5 do not include the following costs. Details will be available on the Exhibitors Manual distributed at orientation for exhibitors.

### 6.1 Booth decorations other than basic panels

Package booth program\*  
Standard package plans for regular exhibitors. Other variations are available. Refer to the Exhibitors Manual for details.

One booth	¥ 90,300 (including tax)	Parapets, cutting sheets for company name lettering, carpeting, reception counter, chairs, spotlights, fluorescent lights, electric outlet
Two booths	¥142,800 (including tax)	
Three booths	¥195,300 (including tax)	

\* Exhibitors at the Emerging Company Area are supplied with special packaged booth at no extra cost. Refer to section 7.4.ii. for details.

### 6.2 Extra power supply

Extra electric power supply lines (exceeding 1kW per booth single-phase or three-phase 200V) are available for the following fees:

Single-phase 100V or 200V	¥8,400/kW (including tax)
Three-phase 200V	¥8,400/kW (including tax)

### 6.3 Installation work for extra electric power supply equipment

### 6.4 Total electricity consumption

Exhibitors bear the following charges for the consumption of electric power, including that of the basic power supply, in accordance with their power supply application:

Electric power consumption	¥2,100/kW (including tax)
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### 6.5 Temporary telephone

Temporary telephones can be installed in booths on request. The following charges include basic installation, line application fees and call charges up to the stipulated amount. If the total of actual charges, including call charges, exceeds these amounts, the exhibitor will be invoiced after the Fair.

Public analog line	¥31,500/line (including tax)
INS 64 line	¥47,250/line (including tax)

Period of operation: January 24–26, 2007

### 6.6 Overtime charges

Exhibitors shall bear overtime work charges if preparation time is required in excess of the specified hours any day before or during the show.

Overtime charge	¥10,500/hour (including tax)
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### 6.7 Additional information leaflets (in Japanese), envelopes and exhibitor/contractor badges

Extra orders (exceeding free-of-charge allotments) will be charged at cost as follows:

Leaflets (over 200 per booth)	¥50/leaflet (including tax)
Envelopes (over 200 per booth)	¥30/envelope (including tax)
Exhibitor Badges (over 10 per booth)	¥50/badge (including tax)
Contractor Badges (over 5 per booth)	¥500/badge (including tax)

## 6.8 Booth administration

Costs related to booth administration include transportation and personnel.

## 6.9 Other

Other expenses may be incurred owing to exhibitor requests and/or legal requirements concerning booth design. Details will be available on the Exhibitors Manual.

## 7 Exhibition Regulations for Emerging Company Area

### 7.1 Exhibition fee: ¥210,000 (including tax)

Note: Exhibit is limited to 1 booth per exhibitor within the Emerging Company Area

### 7.2 Booth specifications: 2,000 mm (W) x 2,000 mm (D)

### 7.3 Usage eligibility: Corporations and/or organizations exhibited up to twice in past EDSFair

### 7.4 Items included in the booth fee:

- i. Display space
- ii. Emerging Company Area special booth unit: including display stand (with drawers), reception counter, chairs, lightings, and electric outlet (1-kW worth)
- iii. Eligibility to use the Special Presentation Stage

### 7.5 Aforementioned sections 1.1 to 1.11 on Scope of Exhibits will apply for exhibition at the Emerging Company Area

### 7.6 Follow the Guide to Exhibition Regulation for other matters not specified above.

## 8 Application and Payment

Fill in the appropriate application form(s) and submit to JESA by post.

- Reception of original forms by post will be the date of receipt. JESA will NOT accept form submissions by fax.
- If you have not exhibited at the EDSFair before, you are required to submit your corporate profile and product catalog along with the application form.

### 8.1 Send to

Japan Electronics Show Association  
Attn.: Ms. Yuka Arikawa, or Mr. Fumiaki Yoshinaga  
5F, Sumitomo Shibadaimon Bldg.  
1-12-16, Shibadaimon, Minato-ku, Tokyo, 105-0012, Japan  
Phone: +81-3-5402-7601 Fax: +81-3-5402-7605

### 8.2 Deadline

#### Early Application: Friday, September 8, 2006

- i. If all available booths are not reserved by the early application deadline, applications will be accepted from September 9, until all booths are sold.
- ii. For applications received after the early application deadline, some arrangements (Web site announcement, etc.) may be delayed compared with early applicants.
- iii. In principle, the final deadline for application is November 10, even if all booths are not sold out.
- iv. If booths remain available after the final deadline, applications may be accepted from the following day. In such cases, however, announcement in information sets may not be possible.

### 8.3 Fee payment

Exhibition fees are to be remitted to one of the following bank accounts upon receipt of an invoice from the Management Office. Payments by promissory note will not be accepted, and bank transfer charges are to be paid by the exhibitor.

#### Account name: Japan Electronics Show Association

Bank (code)	Branch (code)	Account	
		Type	Number
Sumitomo Mitsui (0009)	Marunouchi (245)	Ordinary	6753222
Tokyo-Mitsubishi UFJ (0005)	Head Office (001)	Ordinary	0804757
Mizuho (0001)	Tokyo Chuo (110)	Ordinary	1844192

## 9 Determination of Booth Location

Lots will be drawn to determine booth locations at the orientation for exhibitors held on October 20, 2006. Lotteries will be held among exhibitors with the same numbers and layouts of booths in the order that applications are received.

### 9.1 Primary lottery

For early applications received by September 8, 2006

### 9.2 Secondary lottery

For applications received from September 11 – 29, 2006

### 9.3 Supplementary booths

If booths remain available by the secondary lottery, they will be allotted to each floor as supplementary booths. New applicants on or after October 2 should select their desired locations from among the supplementary booths at the time of application.

## 10 Booth Cancellation/Reduction

Exhibitors who cancel or reduce their booth size for any reason shall bear the following penalties, plus consumption tax.

Date notified	Penalty
Sept. 11 - 29	50% of exhibition fee
Oct. 2 - Nov. 10	80% of exhibition fee
Nov. 13 or after	Entire exhibition fee

Written notification of the intention to cancel or reduce booth size should be sent by fax or e-mail. This notification is valid on the day it arrives at the Management Office.

Note: Exhibitors who cancel or reduce their booth size in Emerging Company Area, Suite, and/or Seminar shall also bear the aforementioned cancellation/reduction penalties.

## 11 Fair Cancellation

If the Fair cannot be held due to a natural disaster such as an earthquake, fire or other calamity beyond human control, fees will be refunded to exhibitors after subtracting necessary expenses incurred up to the date of said calamity. However, the Management Office cannot be held responsible for other expenses incurred by exhibitors.

## 12 Prohibitions and Restrictions

### 12.1 Sales of goods

Under no circumstances may exhibitors sell products on the Fair site.

### 12.2 Disturbing others

- i. Exhibitors are prohibited from distributing questionnaires or soliciting visitors in aisles.
- ii. Exhibitors are prohibited from disturbing other participants and/or visitors by making excessive noise. Should exhibitor require usage of loudspeakers take appropriate preventive measures.
- iii. Should exhibitor require usage of laser beam, steam, gas, smoke or equipment that makes odor or vibration within the premises, take appropriate preventive measures.

Note: For more details, please refer to the Exhibitors Manual

## 13 Responsibility for Exhibits

To the best of its ability, the Management Office will ensure the security of exhibits during the Fair period by means of security guard patrols. However, the Management Office assumes no responsibility for damage or loss through natural disasters, fire, thefts or other events. Exhibitors are encouraged to arrange appropriate measures, such as insurance, for their property at the Fair.

# Guide to Application of Support Services

## 1 Suites

Suites are available in the exhibition hall for exhibitors to conduct business negotiations or demonstrate products to specific customers. Please fill in the designated column in the exhibition application form, and send it to the Management Office.

### 1.1 Dates and times of usage

9:00 a.m. to 7:00 p.m., January 25 & 26, 2007

### 1.2 Room specifications and charges

Type-S	3,960mm (w) x 3,960mm (d) (approx. 16m <sup>2</sup> ) x 2,700mm (h)	¥273,000
Type-M	5,940mm (w) x 3,960mm (d) (approx. 24m <sup>2</sup> ) x 2,700mm (h)	¥336,000
Type-L	5,940mm (w) x 4,950mm (d) (approx. 30m <sup>2</sup> ) x 2,700mm (h)	¥378,000

The above room charges included the following costs:

- 4 walls and 1 door (system panels)
- Carpet
- Signboard with exhibitor's name
- 1.5-kW power source (socket) and electricity consumption
- 40-W fluorescent lights (3 for Type-S, 6 for Type-M, 8 for Type-L)

### 1.3 Maximum rooms available

Booths applied for	Maximum rooms
6 or less	1
8—10	2
12—15	3
16 or more	4

### 1.4 Room allocation

The Management Office will determine room allocation.

### 1.5 Fixtures

The Management Office will provide, on request, detailed information on fixtures such as tables, chairs and reception sets. Applicants must pay actual costs and expenses to use these fixtures. The applicant should prepare demonstration equipment and instruction materials.

### 1.6 Restrictions

- Neither microphones nor speakers are permitted in the suites.
- Suites may not be used either as waiting or stock rooms.
- Re-rental of suites to other companies is not permitted.

### 1.7 Administration

- The suite area will be located in the Exhibition Hall and clearly distinguished from the exhibition area using system panels and other installations.
- The Management Office will be responsible for the suite area, but users should manage their suite rooms.
- The user should arrange escorts to suites. Paging services will not be available.
- A refreshment lounge in the Exhibition Hall will provide food and beverage services for exhibitors and visitors. Users shall bear the relevant costs.
- Two or more adjacent suites can be combined for use as a large room, or the room size can be altered by moving partition walls.

### 1.8 Cancellation and reduction of suite spaces

Exhibitors who cancel or reduce their suite size for any reason shall bear the following penalties, plus consumption tax.

Date notified	Penalty
Sept. 11 - 29	50% of suites charge
Oct. 2 - Nov. 10	80% of suites charge
Nov. 13 or after	Entire suites charge

## 2 Seminars by Exhibitors

Exhibitors can purchase seminar time and use it for presentations of new technologies and products.

Please fill in the designated column in the exhibition application form, and send it to the Management Office.

### 2.1 Available times and dates

10:30 a.m. to 5:15 p.m., January 25 & 26, 2007

[Planned timetable]

Jan. 25	10:30, 11:30, 12:30, 13:30, 14:30, 15:30, 16:30
Jan. 26	10:30, 11:30, 12:30, 13:30, 14:30, 15:30, 16:30

### 2.2 Application

- Each session should be 45 minutes in length or less.
- Any number of sessions can be used for one or multiple topics.
- Exhibitors may apply for up to two consecutive sessions for any one topic.
- Final seminar dates and times will be determined by lottery after the application period.
- If the number of applications exceeds the total available number of sessions, sessions may be limited.

### 2.3 Usage fees (45-minute session)

Room capacity	Price
A-type: Up to 30	¥42,000 (including tax)
B-type: Up to 50	¥63,000 (including tax)
C-type: Up to 100	¥126,000 (including tax)

The above usage fees include the following costs:

- Podium, chairs with writing boards for audience, whiteboard, PA equipment, overhead projector, LCD projector, screen, laser pointer
- Program board in front of the room
- Additional equipment or materials as necessary can be ordered separately. Expenses for such additional materials shall be borne by users.

### 2.4 Seminar objectives

Seminars should be limited to presentations of information, new technologies, new products, and/or progress of technological developments related to the user's exhibit.

### 2.5 Admission

Free

### 2.6 PR assistance

It is generally the responsibility of the user to gather participants for seminars. However, the Management Office will assist users by publicizing the seminar program as follows:

- In the Information Leaflet
- On the Fair Web site
- In the Guidebook distributed to all visitors at the exhibition
- On-site signs including announcements, locations and guidance to locations

### 2.7 Documents

- Users shall prepare seminar documents (50 copies for A-type, 70 for B-type, 120 for C-type).
- User shall arrange for personnel to distribute documents to participants at the seminar location.
- Copies should be prepared at each booth for exhibition visitors who cannot attend seminars.

### 2.8 Audience data and surveys

Visitor data is recorded at the reception desk for each seminar. Reports on audience data will be presented to exhibitors on CD-ROM after the Fair. Exhibitors may use this data for conducting surveys.

### 2.9 Cancellation and Reduction of Seminar Spaces

Exhibitors who cancel or reduce their seminar size for any reason shall bear the following penalties, plus consumption tax.

Date notified	Penalty
Sept. 11 - 29	50% of seminar fee
Oct. 2 - Nov. 10	80% of seminar fee
Nov. 13 or after	Entire seminar fee

### 3 Guidelines for Advertising Placement

Diverse advertising media and services are being planned to enhance exhibition effectiveness at EDSFair. Apply for these services by filling out the appropriate sections of the Application for Exhibition and return it to the Management Office. A special early application discount of 20% will be offered to exhibitors who apply on or before September 8, 2006.

#### 3.1 Ad in Guidebook

- i. Guidebook format: A4 size, approx. 60 pages, offset printing
- ii. Circulation (planned): 15,000
- iii. Publication date: January 25, 2007
- iv. Distribution: Free of charge to EDSFair 2007 visitors
- v. Ad space and price list (including tax)

Ad type	Early applicants	Regular applicants
Inside front cover	¥302,400	¥378,000
Inside back cover	¥277,200	¥346,500
Back cover*	¥336,000	¥420,000
Opposite contents	¥252,000	¥315,000
Article insert, 1 color	¥126,000	¥157,500
Article insert, 2 colors	¥168,000	¥210,000
Article insert, 4 colors	¥252,000	¥315,000

\*Size of Back cover: 180 X 255 mm

- vi. Instructions for camera-ready materials
  - a. Submit camera-ready ad materials. If requesting the printing company to produce these materials, a fee will be charged.
  - b. Produce full-size camera-ready materials.
  - c. Dimensions: (W x H in mm)  
Finished size: 210 x 297\*, printer lines: 216 x 303  
Printed area: 180 x 267  
\*Finished size of Back cover: 180 x 255

- vii. Order of placement  
Ads inserted in articles will be placed in the order applications are received.

#### 3.2 Web Site Banner Ads

- i. Web site: Banner ads will be randomly displayed in a separate frame on the EDSFair 2007 Official Web site ([www.edsfair.com](http://www.edsfair.com)).
- ii. Period of placement:  
Mon., December 4, 2006 – Tue., February 27, 2007
- iii. Size: 40 pixels (H) x 170 pixels (W)
- iv. Price list

	Early applicants	Regular applicants
<b>With ad in Guidebook</b>	¥42,000 (including tax)	¥52,500 (including tax)
<b>Without ad in Guidebook</b>	¥84,000 (including tax)	¥105,000 (including tax)

- v. Format  
Banner file size: Maximum of 10KB  
Banner file formats: GIF, JPEG  
Animated GIF: Up to 2 images may be alternately displayed
- vi. Production services: The Management Office will produce banner ads upon request.

<b>Basic file format</b>	¥52,500 (including tax)
<b>Animated GIF</b>	¥84,000 (including tax)

#### 3.3 Block ads on Fair map

- i. Format: A3 sheet (black and white)
- ii. Circulation (planned): Approx. 10,000
- iii. Distribution: All visitors to EDSFair 2007
- iv. Size of ad space: 5.5 cm (H) x 8.5 cm (W)
- v. Service charges

<b>Early applicants</b>	¥126,000 (including tax)
<b>Regular applicants</b>	¥157,500 (including tax)

- vi. Format: Adobe Illustrator

#### 3.4 Customized message e-Mail-out Service

- i. No. of recipients: Approx. 5,000
- ii. Recipients: Previous visitors and preregistrants for EDSFair 2007
- iii. Dates: On a date of the exhibitor's choice between Dec. 4, 2006, and Jan. 25, 2006. The Management Office may coordinate the order of mail-out dates, in case more than two applicants choose the same date.
- iv. Content of message: Restricted to information about EDSFair 2007 exhibits
- v. Service charges

<b>Early applicants</b>	¥60,000/mail-out (including tax)
<b>Regular applicants</b>	¥75,000/mail-out (including tax)

- vi. Message format  
Preferred mail-out date: [Specify preferred date]  
Body: Up to 70 characters x 17 lines (1,190 characters) of text-only data  
Mail-out Sender Account: Exhibitor name will appear as message sender, so please specify the mail account to be used.  
Note: The EDSFair header and footer will be attached to the body of the message. We will inform you of the content of the header and footer at a later date.

#### 3.5 On-site Signage Ads

Insertion fee (including tax)

<b>Ceiling suspended tapestry above exhibitor's booth</b>	¥400,000 (single side) ¥580,000 (both sides)
<b>Column-wrapped ad</b>	¥150,000
<b>Floor signage ad</b>	¥250,000

Note: Applications for signage ads are available in the Exhibitors Manual distributed at orientation for exhibitors

# New: Emerging Company Area

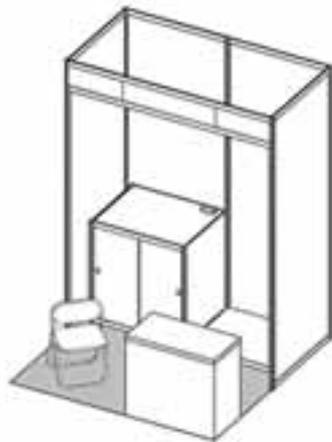
**For emerging companies interested in participating in the fair but do not yet have a booth, this area is a great way to exhibit your technologies or products!**

◇ Low cost yet value-added environment designed to facilitate product introductions by emerging companies.

◇ There are many visitors who are interested in the new technologies and products offered by emerging companies.

## Special Packaged Booth Available:

- Exhibition fee: ¥210,000 (including tax)
- Booth dimensions: 2 meters (W) x 2 meters (D)
- Usage eligibility: Corporations and/or organizations that have displayed products up to twice in past EDSFair exhibitions.



### ■ Accessories included in the booth fee:

- Display stand (with drawers)
- Reception counter • Chairs
- Company name display • Lighting and electric outlet (1kW)

\*For further details, please refer to the Guide to Exhibition Regulations, pages 5 and 6.

## Exhibitor Benefits at the Emerging Company Area

### ■ Use of the Special Presentation Stage

- An open presentation stage will be prepared for exhibitors at the Emerging Company Area and it can be used free of charge.



### ■ PR assistance service

- Promotional activities on the official Web site and for the media will be strengthened to showcase the area as a featured venue of the EDSFair.

### ■ Use of the Communication Area (Open lounge)

- An Open lounge will be available within the area that can be used for taking breaks or for communicating with customers in a relaxed atmosphere.

Note: Target participants are Overseas vendors with or without branch offices or subsidiaries in Japan, which have not exhibited no more than twice in past EDSFair exhibitions.

## The following comments were received from first-time exhibitors at EDSFair 2006

### First time exhibitors at EDSFair 2006

Advanced RFIC (s)  
Aprio  
Axiom Design Automation  
Azuro  
Helic  
Impulse Accelerated Technologies  
Mirabilis Design  
MunEDA  
Pyxis Technology  
SynaptiCAD  
Verific Design Automation

Exhibiting for the first time in Japan, it was very important that our company was able to do this at the EDSFair's Venture Company Pavilion. We found it to be an advantageous setting to present our company and products to Japanese companies and interested customers. We were able to establish excellent contacts while presenting our solutions to booth visitors. I would always recommend that EDA companies new to the Japanese market exhibit their products at the Venture Company Pavilion to ensure a successful and beneficial event.

MunEDA

The EDSFair was well organized, well attended and definitely worth the investment. This event has gained momentum and is now second only to DAC in the US.

Pyxis Technology

The EDSFair proved to be very helpful for meeting with prospective Japanese customers, especially from semiconductor companies that were interested in our Verilog, SystemVerilog, and VHDL parser technologies.

Verific Design Automation

# Visitor Trends at EDSFair 2006

More than 10,000 visitors related to the industry attended EDSFair 2006. It was an ideal venue for cultivating and expanding business opportunities because a large number of visitors related to the industry were there at one venue.

## EDSFair 2006 Visitor Data

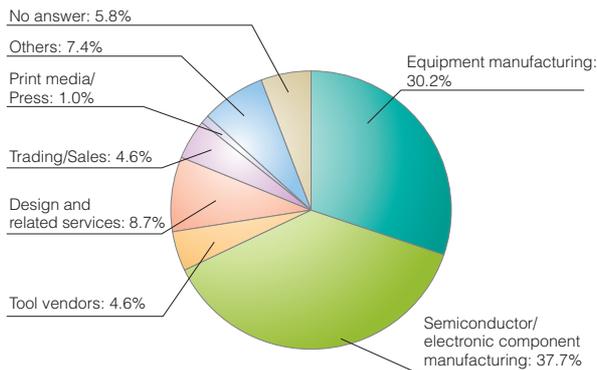
Date	Weather	No. of Visitors	Total
January 26, 2006 (Thu.)	Clear	5,006	—
January 27, 2006 (Fri.)	Clear	5,997	11,003

70.8% of visitors to the EDSFair 2006 spent an average of four to five hours at the fair, enthusiastically looking at products exhibited in booths and attending numerous seminars and conferences. At EDSFair 2007, we will continue to provide valuable, highly desired information to meet visitor expectations.

## The Companies and Visitors Involved in the Exhibition Shared Common Objectives and Desires.

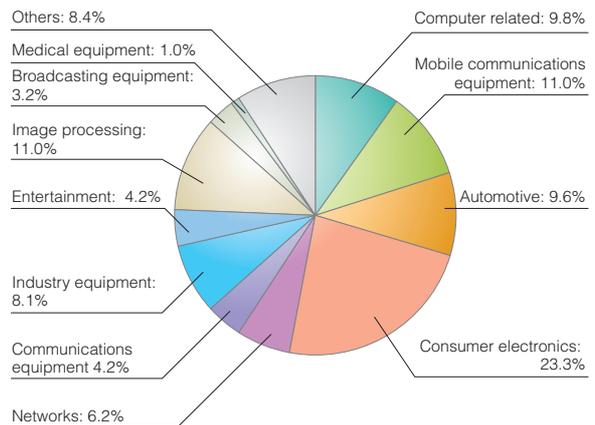
### Business

Visitors were not only from the semiconductor and electronic device/component sectors but also from equipment manufacturers.



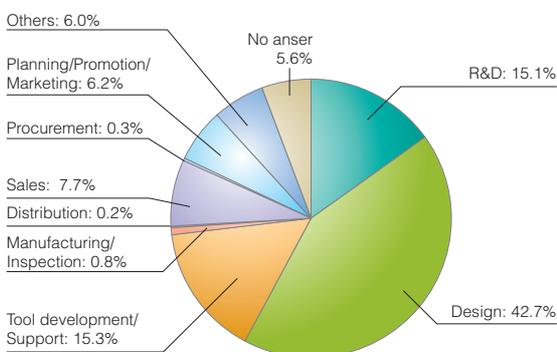
### Application of equipment

Visitors involved with consumer electronics and the handling of a wide variety of equipment have increased.



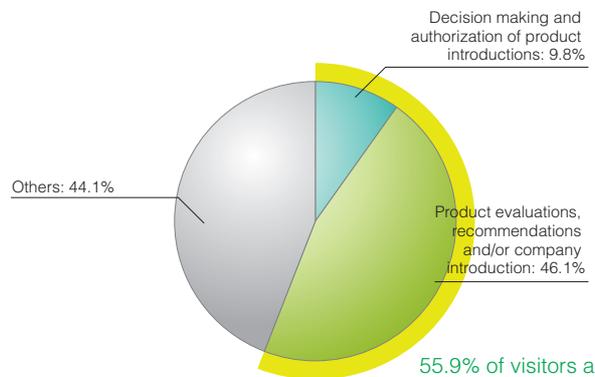
### Occupation

Many visitors were from the research and development fields.



### Involvement in product introduction

55.9% of visitors are involved in the introduction of products.



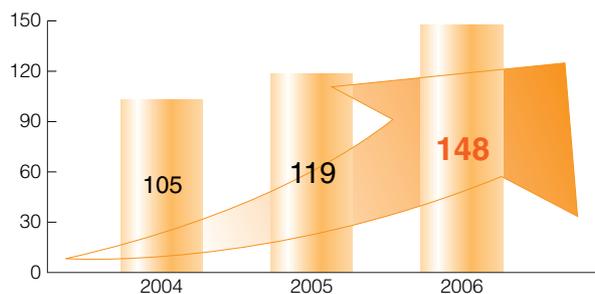
55.9% of visitors are involved in the introduction of products.

## EDSFair 2006 Exhibitors List

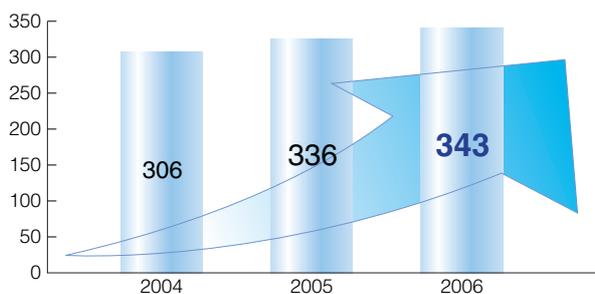
Actel Japan K.K.	IVIS Co., Ltd
ADVANCED RFIC (S) PTE LTD	JAPAN NOVEL CORPORATION
AET, Inc.	ACE Associated Compiler Experts by
Agilent Technologies Japan, Ltd.	Jedat Inc.
ALTERA JAPAN, LTD.	JEVeC
Altium Japan K.K.	KANEMATSU ELECTRONICS LTD
Ansoft Japan K.K.	KeyBridge, Inc.
APACHE DESIGN SOLUTIONS, INC.	Magma Design Automation Co., Ltd.
APPLIED SIMULATION TECHNOLOGY, LTD.	Marubeni Solutions Corp.
Applistar Corp	Mathematical Systems Inc.
APRIO TECHNOLOGIES	Mentor Graphics Japan Co., Ltd.
ARCHPRO DESIGN AUTOMATION INC.	MIRABILIS DESIGN INC
ARM K.K.	MISH INTERNATIONAL CO., LTD.
ASIP Solutions, Inc.	MITSUBISHI ELECTRIC ENGINEERING COMPANY LIMITED
ASTRON, Inc.	MUNEDA GMBH
Atrenta KK	NEC Corporation
AXIOM DESIGN AUTOMATION	NEC Electronics Corporation
AZURO INC	Nihon Eve K.K.
Berkeley Design Automation, Inc.	Nihon Synopsys Co., Ltd.
BRION TECHNOLOGIES KK	NIHON TRANSEDA KK
Cadence Design Systems, Japan	Nikkei Business Publications, Inc.
Innotech Corporation	NIPPON SYSTEMWARE CO., LTD.
Calypto Design Systems K.K.	Non-Profit Organization FPGA Consortium
CARBON DESIGN SYSTEMS, INC.	NOVAFLOW, INC.
CATS Co., Ltd.	Novas Software, Inc
InterDesign Technologies, Inc.	Silicon Canvas, Inc
Celoxica Japan K.K.	Fortelink, Inc
CoWare K.K.	NS Solutions Corporation
M-RF CO., LTD.	NTT Advanced Technology Corporation
CQ Publishing Co., Ltd	AT Design Links Corporation
CRITICALBLUE	Oki Network LSI Co., Ltd.
CYBERNET SYSTEMS CO., LTD.	Patni Computer Systems
CyberTec Ltd.	Platform Computing KK
Jasper Design Automation, Inc.	Proside Corporation
DAIHEN Corporation	PROtotyping Japan Corp.
CAST inc.	Pyxis TECHNOLOGY INC
DAIKIN INDUSTRIES, LTD.	Reed Business Information Japan K.K.
D-CLUE Technologies Co., Ltd.	ROYO ELECTRO CORPORATION
Dempa Publications, Inc.	XILINX
DENALI SOFTWARE K.K.	Semiconductor Technology Academic Research Center
DSM International, Inc.	Sequence Design KK
Virage Logic K.K.	Sierra Design Automation KK
E2Publishing	SIGMA-C K.K.
FORTE DESIGN SYSTEMS	SILICON DESIGN SYSTEMS
FUJITSU LIMITED	SILICON INTEGRATION INITIATIVE
GENESIS TECHNOLOGY INC.	SILISTIX LTD.
GOLDEN GATE TECHNOLOGY, INC	SILVACO Japan Inc.
hdLab, Inc.	SK-Electronics Co., LTD.
Pasona Engineering Inc.	SOLITON SYSTEMS K.K.
HELIC S.A.	Aldec, Inc.
Hitachi Information Technology Co., Ltd.	Interra Systems Inc.
Impinj, Inc.	MOSAID Technologies Inc. (Virtual Silicon)
Impulse Accelerated Technologies Inc	Novocell Semiconductor, Inc.
INNTECH CORPORATION	QualCore Logic, Inc.
Sonics, Inc.	Y Explorations, Inc.
ChipVision Design Systems AG	STEADY DESIGN LTD.
Target Compiler Technologies N.V.	SUMISHO COMPUTER SYSTEMS CORPORATION
Sagantec Israele Ltd.	Summit Design Japan Co., Ltd.
Jazz Semiconductor	SynaptiCAD Inc
Virage Logic Corporation	Synplicity K.K.
Beach Solutions, Inc.	System Fabrication Technologies, Inc.
eASIC	Takumi Technology KK
ISHIZUE Design Automation Corp.	Tanner Research Japan K.K.
ITOCHU TECHNO-SCIENCE Corporation	TATENO DENNOU, INC.
Sun Microsystems K.K	Northwest Logic, Inc.
EMC JAPAN K.K	GIDEL Ltd.
Hummingbird Ltd	TENISON DESIGN AUTOMATION
Celoxica Japan K.K.	TENSILICA
Actis Design, LLC	TOOL CORPORATION
EVE Corporation	VERIFIC DESIGN AUTOMATION
Real Intent, Inc.	VeriSilicon, Inc.
Obsidian Software, Inc.	Zuken Inc.
Sarnoff Corporation	
Prolific, Inc.	
Clear Shape Technologies, Inc.	
MatrixOne, Inc.	

## Exhibit Trends

### Number of visitors



### Number of booths



## EDSFair 2007 Operations Timetable

June 15	Exhibitors' orientation (start accepting applications)
September 8	Deadline for early application (deadline for primary lottery)
September 29	Deadline for secondary application (deadline for secondary lottery)
October 20	Booth location drawing and orientation for exhibitors
October 31	Booth fee payment due date for early applicants
November 10	Final deadline for application
November 30	Booth fee payment due date for secondary applicants
December 1	Release of exhibitors information, start of preliminary registration for ad placement in information leaflet and Web site, press release distribution, e-mail-out service, and other promotional activities
January 25 & 26	EDSFair 2007
January 29	Summary report on the number of visitors
March 31	Deadline for remaining fee payments

Note: Aforementioned schedule may change without prior notice.

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